

CLAIMS

1. A method of manufacturing a multilayer circuit board, in which a plurality printed board are stacked and pressed into a multilayer circuit board, each printed board having a conductor layer on one side of an insulating layer, characterized by the steps of stacking the printed boards with a bonding layer being interposed between the printed boards, and stacking an outermost conductor layer on an insulating layer side of a first outermost printed board with a bonding layer being interposed therebetween and pressing a stack so that the printed boards and the outermost conductor layer are bonded together, the first outermost printed board being disposed with the insulating layer side being directed outward.

2. A method of manufacturing according to claim 1, characterized in that the printed boards include a second outermost printed board disposed with a conductor layer side being directed outward, the conductor layer being pressed under a condition where the conductor layer has a uniform thickness all over.